

| External_Type | Material_Group | Substances | CAS_Number | Mass | Mass_Percentage_in_Leaf | Massmg |
|----------------|-----------------|---|-----------------|-----------------|-------------------------|--------------|
| Die | Doped Silicon | Silicon (Si) | 7440-21-3 | 1.0789 | 100.0 | 64.96 |
| | | | Subtotal | 1.0789 | 100 | 64.96 |
| Lead Frame | Copper alloy | Phosphorous (P) | 7723-14-0 | 0.01988 | 0.03 | 1.197 |
| | Copper alloy | Iron (Fe) | 7439-89-6 | 0.06627 | 0.1 | 3.99 |
| | Copper alloy | Copper (Cu) | 7440-50-8 | 66.18235 | 99.87 | 3,984.813 |
| | | | Subtotal | 66.2685 | 100 | NaN |
| Mould Compound | Polymer | Phenol Formaldehyde resin (generic) | 9003-35-4 | 2.0652 | 6.5 | 124.345 |
| | Polymer | Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic) | 29690-82-2 | 5.08357 | 16.0 | 306.08 |
| | Filler | Silica fused | 60676-86-0 | 22.55836 | 71.0 | 1,358.23 |
| | Flame retardant | Metal hydroxide | | 2.0652 | 6.5 | 124.345 |
| | | | Subtotal | 31.77233 | 100 | NaN |
| Post-plating | Lead alloy | Tin (Sn) | 7440-31-5 | 0.36539 | 100.0 | 22 |
| | | | Subtotal | 0.36539 | 100 | 22 |
| Wire | Pure metal | Aluminium (Al) | 7429-90-5 | 0.26574 | 100.0 | 16 |
| | | | Subtotal | 0.26574 | 100 | 16 |
| Solder Wire | Lead alloy | Tin (Sn) | 7440-31-5 | 0.01246 | 5.0 | 0.75 |
| | Lead alloy | Silver (Ag) | 7440-22-4 | 0.00623 | 2.5 | 0.375 |
| | Lead alloy | Lead (Pb) | 7439-92-1 | 0.23044 | 92.5 | 13.875 |
| | | | Subtotal | 0.24913 | 100 | 15 |
| | | | Total | 99.99999 | 100 | NaN |

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